# multicomp PRO

RoHS Compliant



#### **Features**

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- · For surface mounted applications
- · Built-in strain relief,ideal for automated placement
- · Low reverse leakage
- · High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

#### Absolute Maximum Ratings (Ta = 25°C Unless otherwise specified)

Parameter	Symbol	SS545L Value	Unit
Maximum repetitive peak reverse voltage	Vrrm	45	
Maximum RMS voltage	VRMS	31.5	V
Maximum DC blocking voltage	VDC	45	
Maximum average forward rectified current at T∟=100°C	I(AV)	5	А
Peak forward surge current, 8.3ms single halfsine-wave superimposed on rated load	Ifsм	120	
Maximum instantaneous forward voltage at 5A	VF	0.48	V
Maximum DC reverse current T <sub>A</sub> =25°C	1-	0.5	A
at rated DC blocking voltage T <sub>A</sub> =125°C	<b>I</b> R	50	- mA
Typical thermal resistance	R <sub>q</sub> JA	80	°C/W
Operating Junction Temperature Range	Тл	-55 to +150	°C
Storage Temperature Range	Тѕтс	-55 to +150	°C

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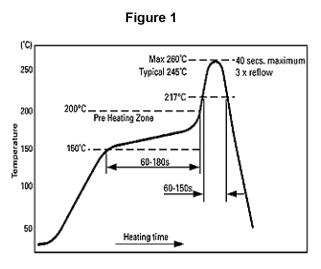


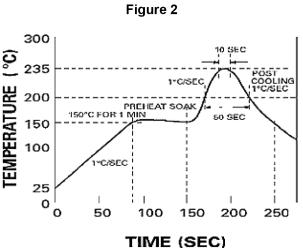
#### **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





#### Reflow profiles in tabular form

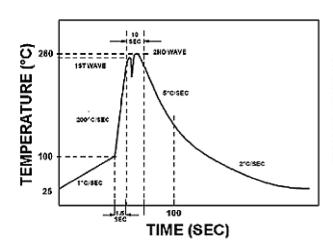
Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat  – Temperature Range  – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above:  - Temperature  - Time	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.

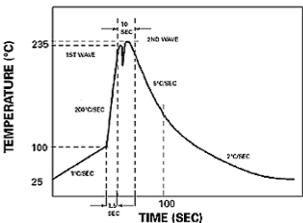


#### **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





#### **Wave Profiles in Tabular Form**

Profile Feature	Sn-Pb System	Pb-Free System	
Average Ramp-Up Rate	~200°C/second	~200°C/second	
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec	
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp	
Peak Temperature	235°C	260°C max.	
Time within +0 -5°C of actual Peak	10 seconds	10 seconds	
Ramp-Down Rate	3°C/second max.	5°C/second max.	

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#### **Typical Characteristic Curves**

Fig 1: Derating Curve Output Rectified Current

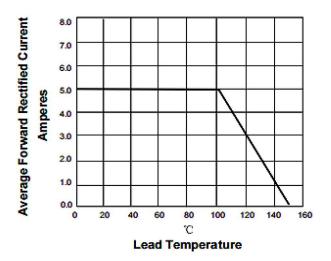


Fig 3: Maximum Non-Repetitive Peak Forward Surge Current Per leg

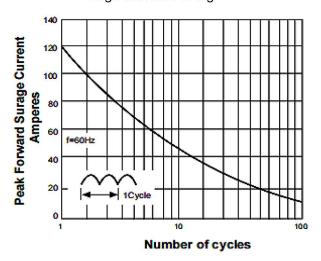


Fig 2: Typical Forward Voltage Characteristics

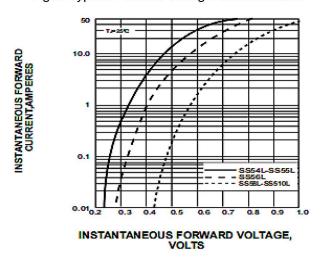
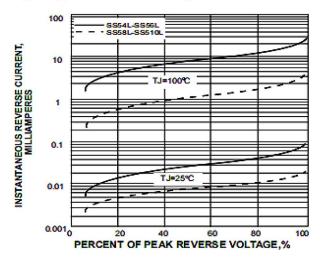
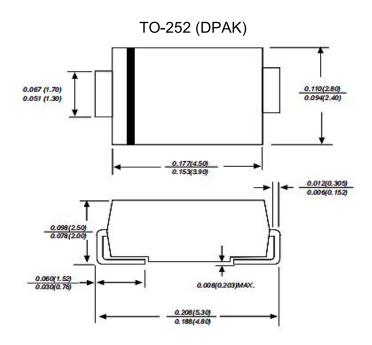


Fig 4: Typical Reverse Leakage Characteristics



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#### **Dimensions**



#### **Part Number Table**

Description	Part Number
Schottky Barrier Rectifier, Surface Mount, 5.0Amp	SS545L

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